EXHIBIT B

Final DI only cleaning test

Wafer	pre-count @ >.16	pre-count @ >.2	post-count @ >.16	post-count @ >.2
1	298	79	14	6
2	241	112	9	2
3	38	20	19	7
4	43	14	14	5
5	46	16	24	4
6	41	15	24	5
7	44	14	26	6
8	52	20	24	6
9	37	6	33	16
10	39	13	22	7
11	48	18	16	1
12	61	16	18	8
13	41	20	33	20
14	59	17	23	10
15	66	24	43	18
	Average particles @ > .16 microns (pre) 76.93	Average particles @ > .20 microns (pre) 26.93	Average particles @ > .16 microns (post) 22.80	Average particles @ > .20 microns (post) 8.07
	Average particle removal at > .16 microns		(54.13)	
	Average particle removal at > .20 microns		(18.87)	

Wafers 1 and 2 were the main reason for high average particle removal rate. The results of the removal rate average are quite impressive. The BPT One Brushes show better cleaning performance then any other brush I have used. The removal rates generally average from adding 2 particles to removing 3 particles at .2 microns. By removing wafers no. 1 and 2, the removal rate at .16 was -22.77 and at .20 microns -7.89 average. This data shows that the BPT One brushes clean twice as good then Rippey brushes and their equivalent. Of special note in this test, wafer no. 9 was the only wafer to add particles. This is due because originally the wafer showed a scratch across the wafer on the Tencor. It turned out to be a solid line of particles. During post reading, almost all the particles were removed and the wafer no longer had a scratch count. This is the type of issue I mentioned above about smaller particles causing loss of Die.

AREA

Data thrown out due to bad wafers

	Pre BPT area	Post BPT area	Delta BPT area	Pre b area	Post b area	Delta b area	Pre c area	Post c area	Delta c area
1	30	9	-21	10	3	-7	9	9	0
2	12	7	-5	17	2	-15	14	9	-5
3	16	1	-15	6	2	-4	12	12	0
4	14	1	-13	7	4	-3	8	5	-3
5	3	1	-2	13	3	-10	11	7	-4
6	10	6	-4	14	7	-7	13	6	-7
7	10	1	-9	3	1	-2	10	6	-4
8	5	3	-2	11	3	-8	17	8	-9
9	3	0	-3	7	7	0	17	7	-10
10	6	3	-3				21	4	-17
11	9	4	-5				19	5	-14
12	19	16	-3				9	4	-5
13	7	3	-4				9	2	-7
14	10	6	-4				12	5	-7
15	12	5	-7	25	5	-20	41	12	-29
Totals:			-100			-76			-121

Total Defect

Data thrown out due to bad wafers

	Pre BPT Tot. Def.	Post BPT Tot. Def	Delta BPT Tot. Def	Pre b Tot. Def	Post b Tot. Def	Delta b Tot. Def	Pre c Tot. Def	Post c Tot. Def	Delta c Tot. Def
1	347	199	-148	223	78	-145	151	140	-11
2	158	88	-130	383	82	-301	355	131	-224
3	117	69	-48	78	39	-39	179	193	14
4	186	110	-76	125	61	-64	128	54	-74
5	123	74	-49	51	39	-12	170	151	-19
6	160	98	-62	175	56	-119	125	66	-59
7	242	72	-170	137	32	-105	288	95	-193
8	129	105	-24	91	54	-37	171	94	-77
9	162	44	-118	87	61	-26	300	77	-223
10	326	62	-264				297	67	-230
11	244	51	-193				407	82	-325
12	208	190	-18				69	85	16
13	204	74	-130				89	79	-10
14	93	120	27				59	104	45
15	111	75	-36	115	70	-45	163	70	-93
Totals:			-1439			-893			-1463

Scratch Defect

Data thrown out due to bad wafers

	Pre BPT SCR.	Post BPT SCR	Delta BPT SCR	Pre b SCR	Post b SCR	Delta b SCR	Pre c SCR	Post c SCR	Delta c SCR
1	12	10	-2	0	1	1	6	5	-1
2	5	7	-2	8	2	-6	8	3	-5
3	3	1	-2	6	1	-5	6	7	1
4	4	1	-3	5	2	-3	0	0	0
5	5	5	0	0	0	0	3	2	-1
6	2	0	-2	3	1	-2	3	0	-3
7	3	2	-1	2	2	0	5	3	-2
8	5	6	1	1	2	1	5	1	-4
9	1	0	-1	0	1	1	13	4	-9
10	10	5	-5				5	0	-5
11	4	1	-3				12	3	-9
12	7	2	-5				0	1	1
13	2	0	-2				2	1	-1
14	1	1	0				2	2	0
15	2	0	-2	0	0	0	5	2	-3
Totals:			-29			-13			-41